

AMENDMENTS TO THE SPECIFICATION

Please amend the specification as follows:

Insert on page 1 the following paragraph before the first paragraph:

This is a Divisional of U.S. Patent Application No. 09/787,139, which entered National Stage on March 14, 2001, and which is a §371 National Stage application of International Application No. PCT/JP99/05003, filed September 14, 1999.

Amend the sixth full paragraph on page 21 as follows:

DETAILED ~~DISCRPTION~~ DESCRIPTION OF THE INVENTION

The present invention is now described in detail. Unless otherwise indicated, the thickness of any copper foil, conductor layer or conductor circuit as mentioned in this specification is the mean of thicknesses measured on a light or electron microphotograph of its cross-section.

Amend the last paragraph on page 80 as follows:

The results of this evaluation are presented in ~~Table 1~~ Figure 4. The smaller the value is, the higher is the uniformity of electrodeposition.

Amend the first full paragraph on page 81 following Table 1 (lines 12-15) as follows:

It can be seen from the data in ~~Table 1~~ Figure 4 that, of the above-mentioned four different electroplating techniques, the constant-voltage pulse plating technique provides the highest electrodeposition uniformity.

Amend the paragraph bridging pages 136 and 137 as follows:

As to the multilayer printed circuit board according to Example 17, solder bumps 6076U, 6076D were disposed at the position a little far from the plated-through holes 6036. On the other hand, as to the multilayer printed circuit board

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according to Example 22, solder bumps 6076U, 6076D were disposed immediately over the upper via holes 6160. Therefor, the multilayer printed circuit board according to Example ~~21~~ 22 had an advantage that the plated-through hole 6036, lower-layer via hole 6060, upper-layer via hole 6160 and solder bumps 6076U, 6076D can be lined up in good registration so that the wiring length can be reduced to increase the transmission speed of signals, and a large amount of power can be obtained instantaneously from the power layer.